

ABSTRACT

A heating device within an integrated circuit includes a first conductive lead, a second conductive lead and a third conductive lead. A first resistive region is connected between the first conductive lead and the third conductive lead. A second resistive region is connected between the second conductive lead and the third conductive lead. A side formed by the first conductive lead and the first resistive region is parallel to a side formed by the second conductive lead and the second resistive region.